

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology
- ★ 100% EAS Guaranteed

Product Summary



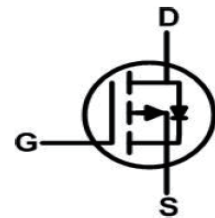
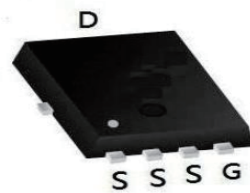
BVDSS	RDS(on)	ID
-30V	7.5mΩ	-55A

Description

The 60P03D is the high cell density trenched P-ch MOSFETs, which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications.

The 60P03D meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

PDFN3\*3 Pin Configuration



Absolute Maximum Ratings (TA=25°C unless otherwise specified)

Symbol	Parameter	Max.	Units
V <sub>DSS</sub>	Drain-Source Voltage	-30	V
V <sub>GSS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Continuous Drain Current	T <sub>A</sub> = 25°C	-55
		T <sub>A</sub> = 100°C	-30
I <sub>DM</sub>	Pulsed Drain Current <sup>note1</sup>	-168	A
E <sub>AS</sub>	Single Pulsed Avalanche Energy <sup>note2</sup>	45	mJ
P <sub>D</sub>	Power Dissipation	T <sub>A</sub> = 25°C	37
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to +150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance from Junction-to-Ambient <sup>note3</sup>	---	75	°C/W
R <sub>θJC</sub>	Thermal Resistance from Junction-to-Case	---	3.36	°C/W

**Electrical Characteristics ( $T_J = 25^\circ\text{C}$  unless otherwise specified)**

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Static Characteristics</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = -250\mu A$	-30	-	-	V
$I_{GSS}$	Gate-body Leakage current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA
$I_{DSS}$	Zero Gate Voltage Drain Current	$T_J = 25^\circ\text{C}$	-	-	-1	$\mu A$
		$T_J = 100^\circ\text{C}$	-	-	-100	
$V_{GS(th)}$	Gate-Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1	-	-2.5	V
$R_{DS(on)}$	Drain-Source On-Resistance <sup>4</sup>	$V_{GS} = -10V, I_D = -30A$	-	7.5	14	m $\Omega$
		$V_{GS} = -4.5V, I_D = -15A$	-	10	22	
$g_{fs}$	Forward Transconductance <sup>4</sup>	$V_{DS} = -5V, I_D = -30A$	-	57	-	S
<b>Dynamic Characteristics</b> <sup>5</sup>						
$C_{iss}$	Input Capacitance	$V_{DS} = -15V, V_{GS} = 0V,$ $f = 1\text{MHz}$	-	2396	-	pF
$C_{oss}$	Output Capacitance		-	325	-	
$C_{rss}$	Reverse Transfer Capacitance		-	283	-	
$R_g$	Gate Resistance	$f = 1\text{MHz}$	-	10.5	-	$\Omega$
<b>Switching Characteristics</b>						
$Q_g$	Total Gate Charge	$V_{GS} = -10V, V_{DS} = -15V,$ $I_D = -30A$	-	30	-	nC
$Q_{gs}$	Gate-Source Charge		-	5	-	
$Q_{gd}$	Gate-Drain Charge		-	7.5	-	
$t_{d(on)}$	Turn-On Delay Time	$V_{GS} = -10V, V_{DD} = -15V,$ $R_G = 3\Omega, I_D = -30A$	-	14.1	-	ns
$t_r$	Rise Time		-	20	-	
$t_{d(off)}$	Turn-Off Delay Time		-	94	-	
$t_f$	Fall Time		-	65	-	
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F = -30A, dI/dt =$ $100A/\mu s$	-	19	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		-	9	-	nC
<b>Drain-Source Body Diode Characteristics</b>						
$V_{SD}$	Diode Forward Voltage <sup>4</sup>	$I_S = -1A, V_{GS} = 0V$	-	-	-1.2	V
$I_S$	Continuous Source Current	$T_C = 25^\circ\text{C}$	-	-	-55	A

Note :

1. Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)} = 150^\circ\text{C}$ .
2. The EAS data shows Max. rating . The test condition is  $V_{DD} = -25V, V_{GS} = -10V, L = 0.1\text{mH}, I_{AS} = -30A$ .
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
5. This value is guaranteed by design hence it is not included in the production test.

Typical Performance Characteristics

Figure 1: Output Characteristics

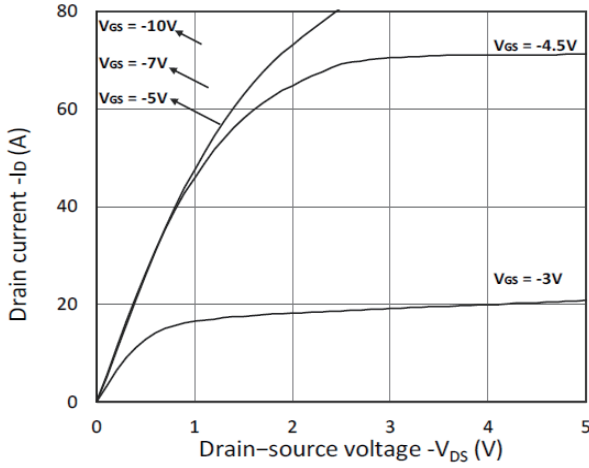


Figure 2: Typical Transfer Characteristics

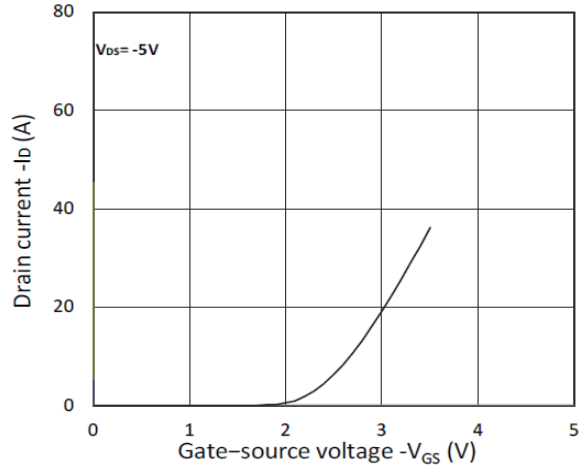


Figure 3: Forward Characteristics of Reverse

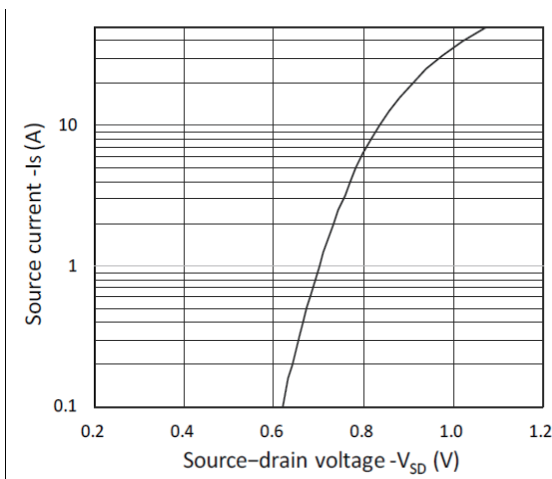


Figure 4: RDS(ON) vs. VGS

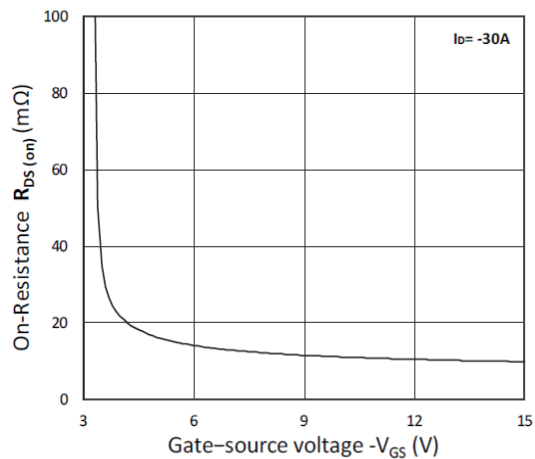


Figure 5: RDS(ON) vs. ID

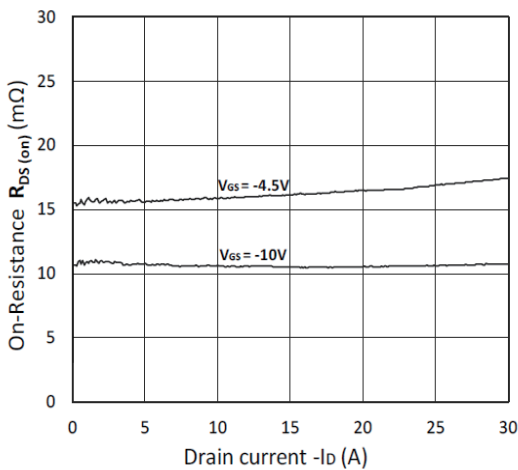
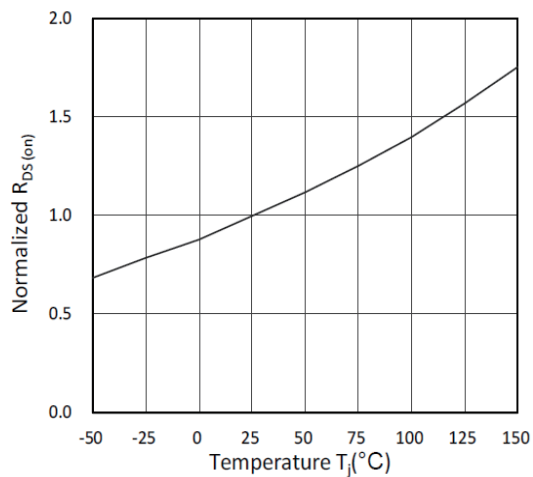


Figure 6: Normalized RDS(on) vs. Temperature



Typical Performance Characteristics

Figure 7: Capacitance Characteristics

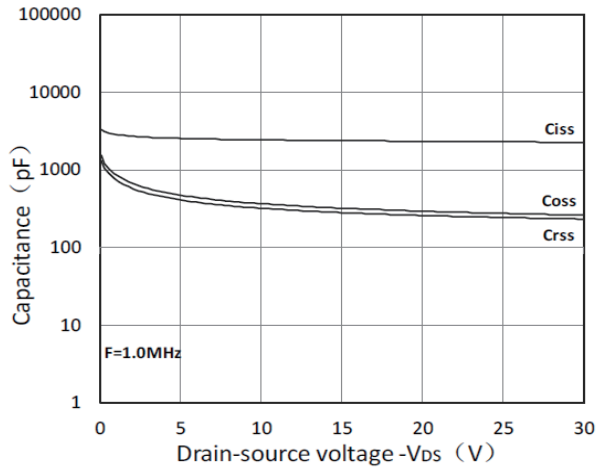


Figure 8: Gate Charge Characteristics

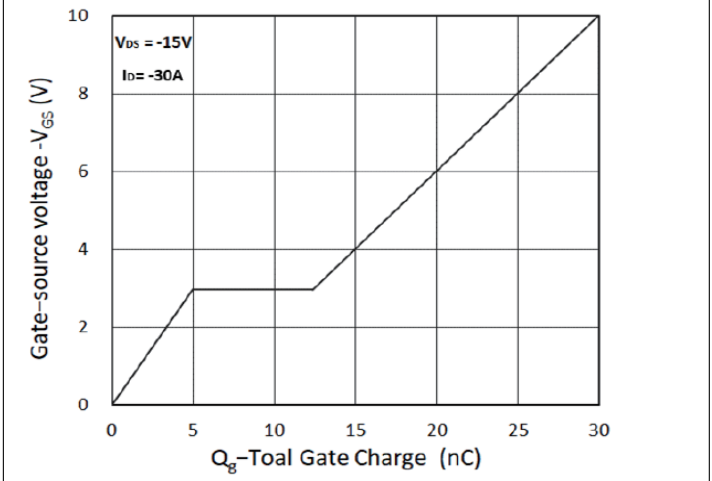


Figure 9: Power Dissipation

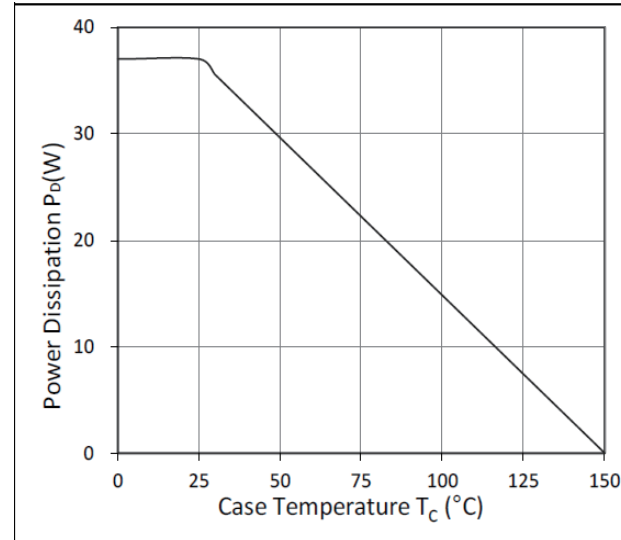


Figure 10: Safe Operating Area

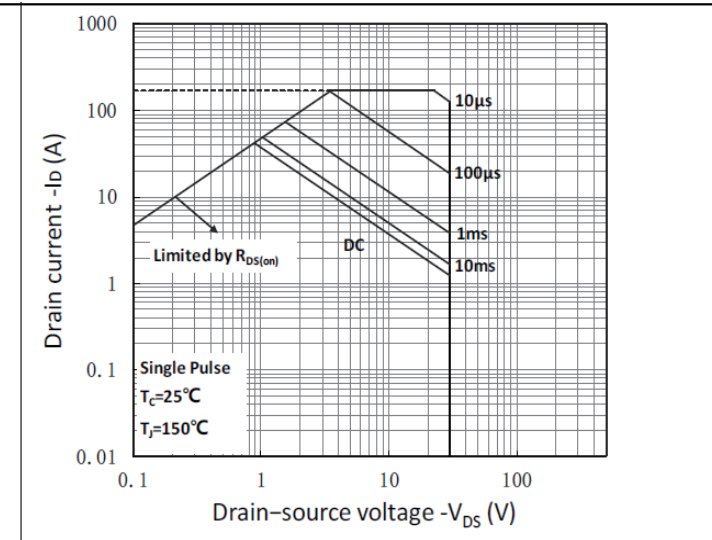
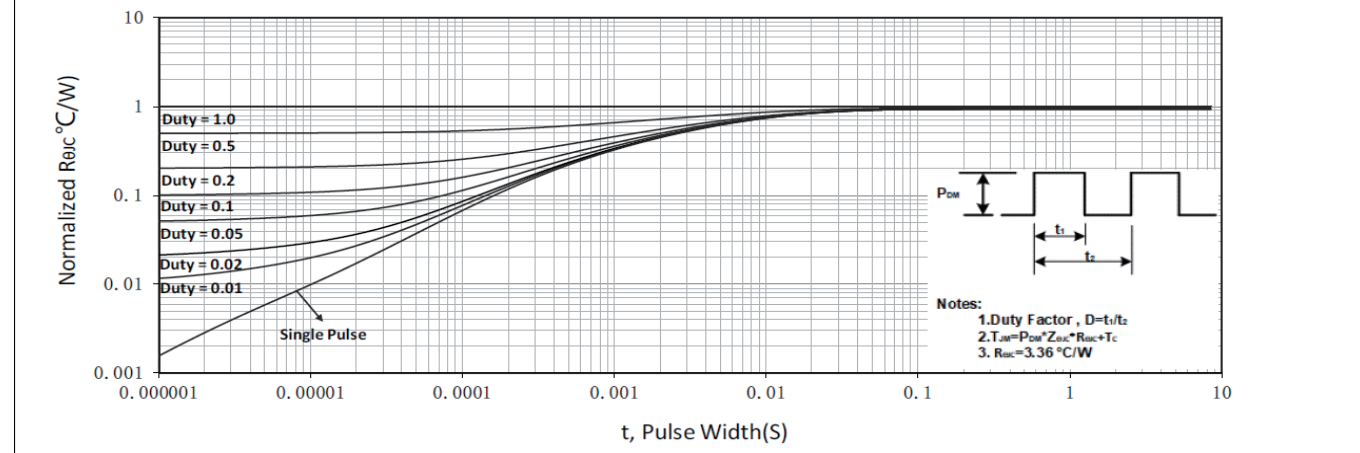
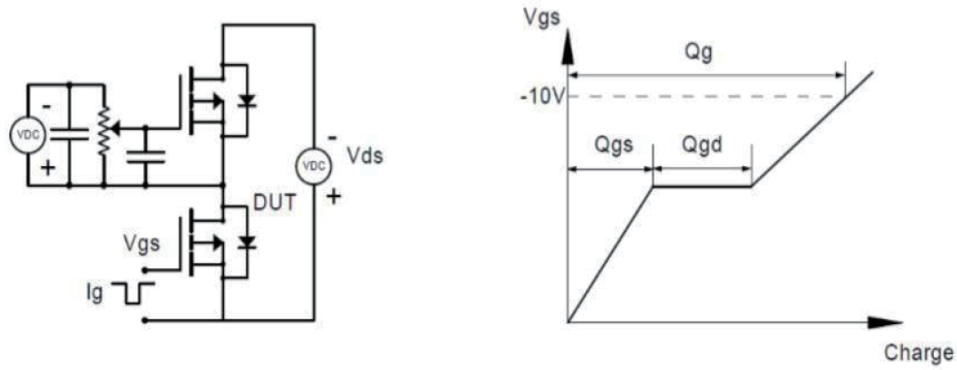


Figure 11: Normalized Maximum Transient Thermal Impedance

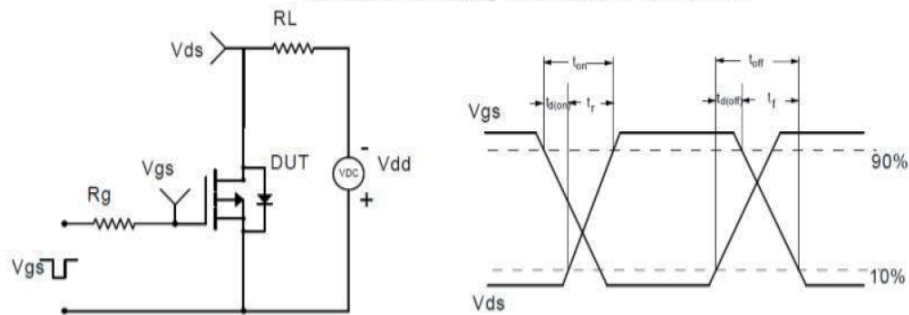


Test Circuit

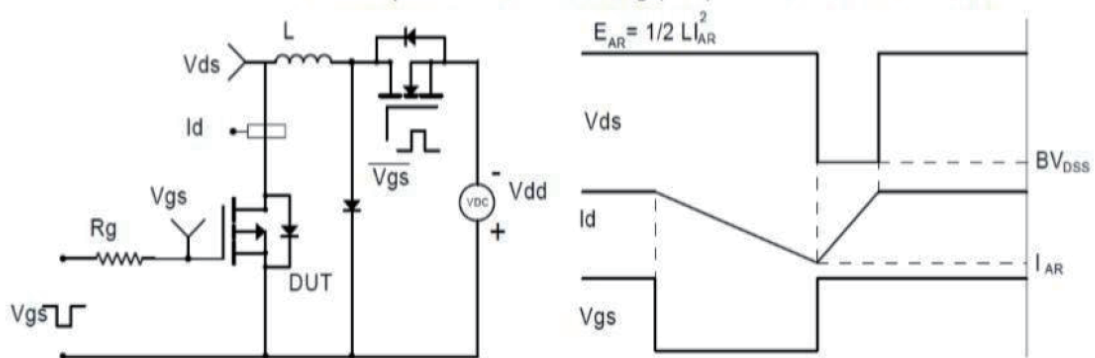
Gate Charge Test Circuit & Waveform



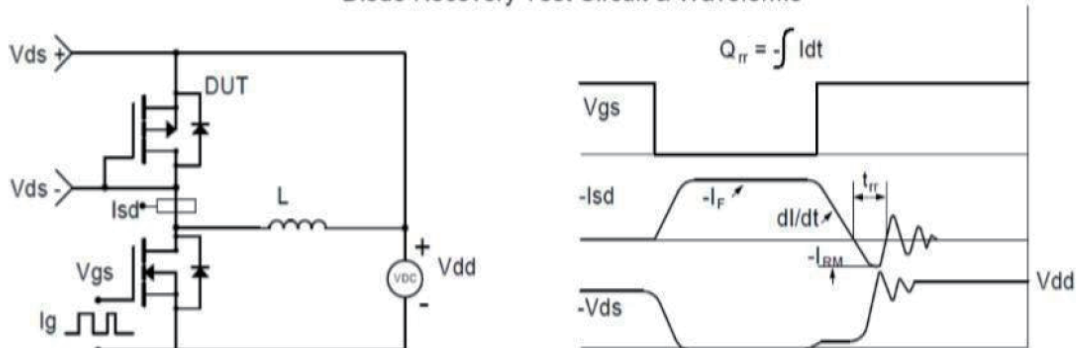
Resistive Switching Test Circuit & Waveforms

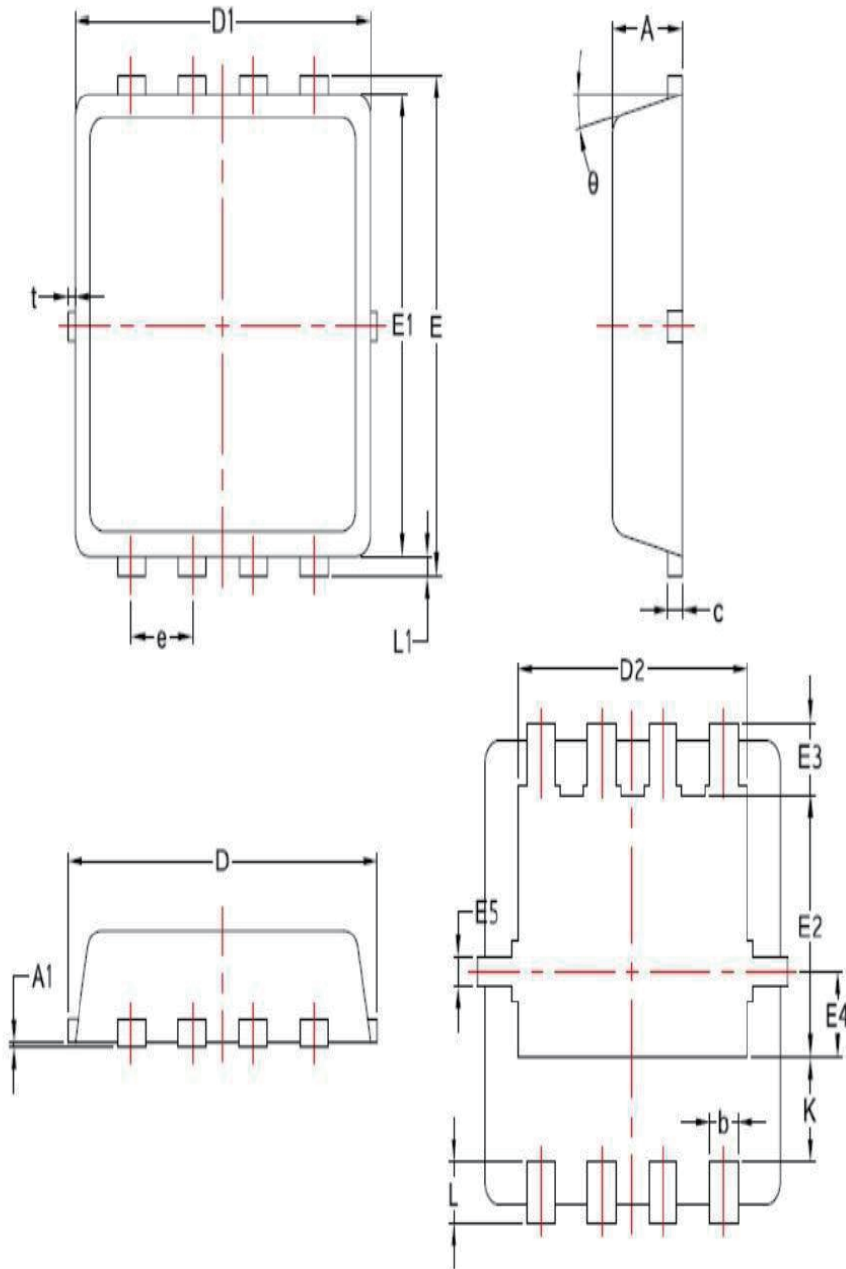


Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms





SYMBOL	COMMON		
	MM		
	MIN	NOM	MAX
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
$\theta$	10°	12°	14°